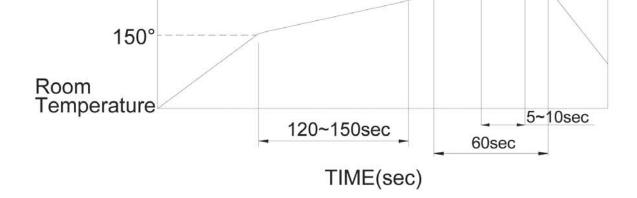


4. Test Sequence:

		ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
	APPEARANCE	1	Visual Examination	By visual examination check without and out pressure & testing.	There shall be no defects that affect the serviceability of the product
	ELECTRIC PERFORMANCE	2	Contact Resistance	Applying a static load 1.5-2 times the operating force to the center of the stem, measurements shall be made with a 1 kHz small current contact resistance meter	100mΩ Max
		3	Insulation Resistance	Measurements shall be made following application of 500 V DC potential across terminals and cover for 1 minute ± 5 seconds	100MΩ min
Ш		4	Dielectric Withstanding Voltage	250 V AC(50Hz or 60Hz) shall be applied across terminals and cover for 1 minute	There shall be no breakdown or flashover
		5	Capacitance	1 MHz ±10 kHz	5 pF max.
		6	Bounce	3 to 4 operations at a rate of 1 cycles per second Switch Synchroscope 5V DC 5ΚΩ	5 m seconds max.

\neg			otom to a stop small be measured	0/0.0±0.2mm 00 07 1
	9	Stop Strength	Placing the switch such that the direction of switch operation is vertical, a static load of 3 kgf(29.4N) shall be applied in the direction of stem operation for a period of 15 seconds	1)As shown in item 4~7 2)Contact Resistance: 200 mΩ Max 3)Insulation Resistance: 10 MΩ min
	10	Solder Heat Resistance	 Through Hole Type 1)Soldering Temperature: 260±5℃ 2)Duration of Solder Immersion: 5±1 sec 3)Frequency of Soldering Process 2 times max. (PCB is 1.6mm in thickness) 4) SMT Type ~ Series(4/4) 	1)Shall be free from pronounced backlash and falling-off or breakage terminals 2)As shown in item 4 · 5 3)Contact Resistance: 200 mΩ Max 4)Insulation Resistance: 10 MΩ min
	11	Vibration	Shall be vibrated in accordance with Method 201A of MIL-STD-202F 1)Frequency: 10-55-10Hz in 1-min/cycle. 2)Direction: 3 vertical directions including the directions of operation 3)Test time:2 hours each direction 4) Swing distance=1.5mm	1)As shown in item 4~7 2)Contact Resistance: 200 mΩ Max 3)Insulation Resistance: 10 MΩ min
_	12	Shock	Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F 1)Acceleration; 50G 2)Action time:11±1m seconds 3)Testing Direction: 6 sides 4)Test Cycle:3 times in each direction	Ditto
	13	Solderability	1)Through Hole Soldering Temperature: 245±3℃ 2)Lead-Free solder: M705E JIS Z 3282 A (Tin 96.5%, Silver 3%, Copper 0.5%) 3)Flux: 5~10 sec 4)Duration of solder Immersion: 5±1 sec	was requested.

DURABILITY	15	Operating Life	test forth below: 1)5mA,5 V DC resistive load 2)Applying a static load the operating force to the center of the stem in the direction of operation 3)Static Load = OF max. 4)Cycle of Operation: 100,000 cycles~66N \ 68S \ 677T 500,000 cycles~67 \ 69 \ 65 \ 64R \ N \ T 300,000 cycles~65 \ 69 \ 67Y	2)Operating force:±50% of initial force 3)Contact Resistance: 10Ω Max 4)Insulation Resistance: 10ΜΩ min 5)Bounce: 10 m seconds Max
	16	Resistan ce Low Temperat ure	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for 1 hour before the measurements are made: 1)Temperature:-25±3°C 2)Time:96 hours	1)As shown in item 4~7 2)Contact Resistance: 200 mΩ Max 3)Insulation Resistance: 10 MΩ min
WEATHER-PROOF	17	Resistan ce High Temperat ure	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: 1)Temperature:80±2°C 2)Time:96 hours	Ditto
M.	18	Resistan ce Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: 1)Temperature:40±2°C 2)Relative Humidity:90~95% 3)Time:96 hours	Ditto



■ The condition mentioned above is the temperature on the Cu foil of the PCB surface.

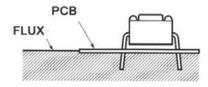
There are cases where board's temperature greatly differs from switch's surface temperature depending on board's material, size, thickness, etc. Care, therefore, should be used not to allow switch's surface temperature to exceed 260°C.

Manual Soldering

Soldering Temperature	Max.350°C	
Continuous Soldering Time	Max. 5 seconds	

■ Precautions in Handling

- Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
- Please make sure that there is no flux rose over the surface of the PCB.
- 3. Please make sure that there is no flux rose over the surface of the PCB



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